



1.0A Surface Mount Fast Recovery Rectifiers-50-1000V

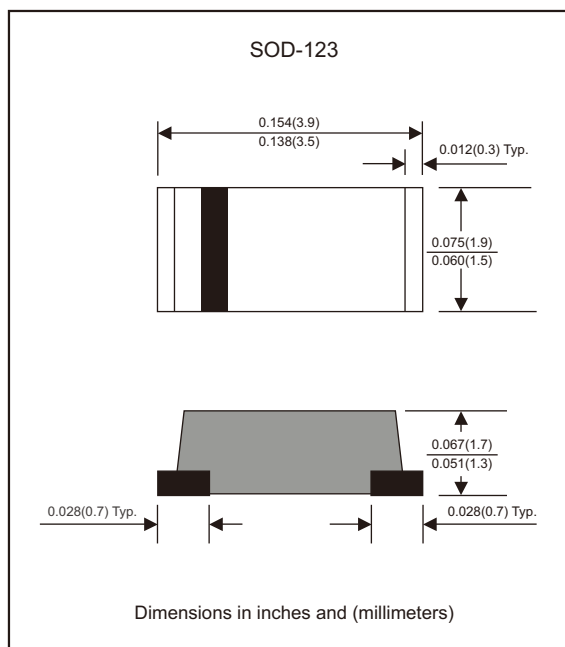
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- High current capability.
- Fast switching for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex. FFM101-M-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123 / MINI SMA
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.018 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

| PARAMETER | CONDITIONS | Symbol | MIN. | TYP. | MAX. | UNIT |
|----------------------------|---|-----------|------|------|------|--------------------|
| Forward rectified current | See Fig.2 | I_O | | | 1.0 | A |
| Forward surge current | 8.3ms single half sine-wave superimposed on rate load (JEDEC methode) | I_{FSM} | | | 30 | A |
| Reverse current | $V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$ | I_R | | | 5.0 | μA |
| | $V_R = V_{RRM} \quad T_J = 125^{\circ}\text{C}$ | | | | 100 | |
| Diode junction capacitance | f=1MHz and applied 4V DC reverse voltage | C_J | | 15 | | pF |
| Storage temperature | | T_{STG} | -65 | | +175 | $^{\circ}\text{C}$ |

| SYMBOLS | V _{RRM} ^{*1} (V) | V _{RMS} ^{*2} (V) | V _R ^{*3} (V) | V _F ^{*4} (V) | t _{rr} ^{*5} (ns) | Operating temperature T _v (°C) |
|----------|---------------------------------------|---------------------------------------|-------------------------------------|-------------------------------------|---------------------------------------|--|
| FFM101-M | 50 | 35 | 50 | 1.30 | 150 | -55 to +150 |
| FFM102-M | 100 | 70 | 100 | | | |
| FFM103-M | 200 | 140 | 200 | | | |
| FFM104-M | 400 | 280 | 400 | | 250 | |
| FFM105-M | 600 | 420 | 600 | | | |
| FFM106-M | 800 | 560 | 800 | | | |
| FFM107-M | 1000 | 700 | 1000 | | 500 | |

Note 1. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I=1.0\text{A}$
- *5 Maximum Reverse recovery time, note 1



Rating and characteristic curves (FFM101-M THRU FFM107-M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

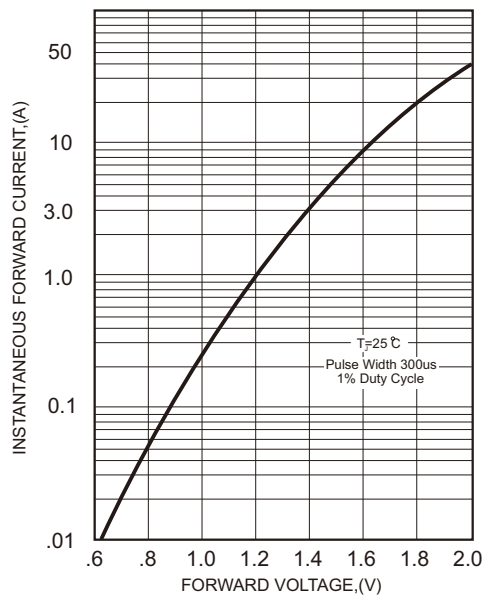


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

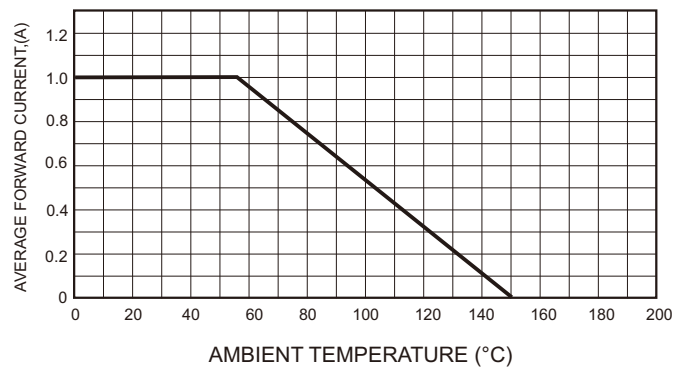
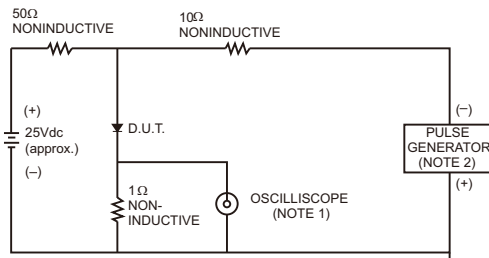


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

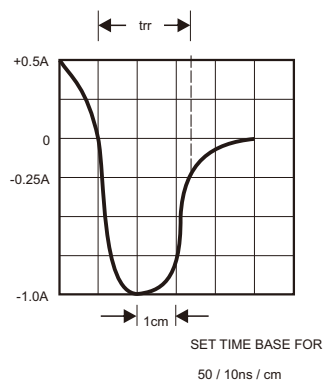


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

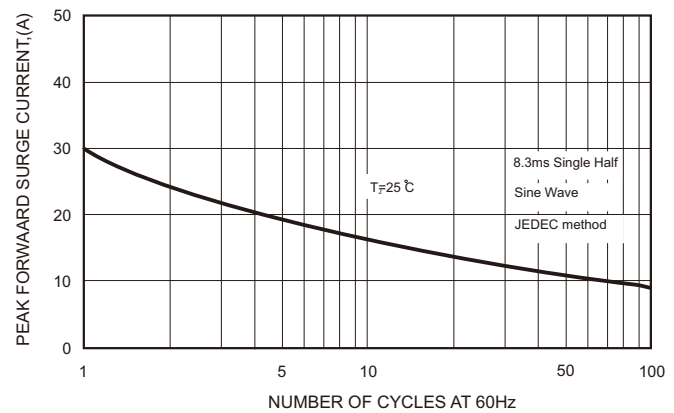
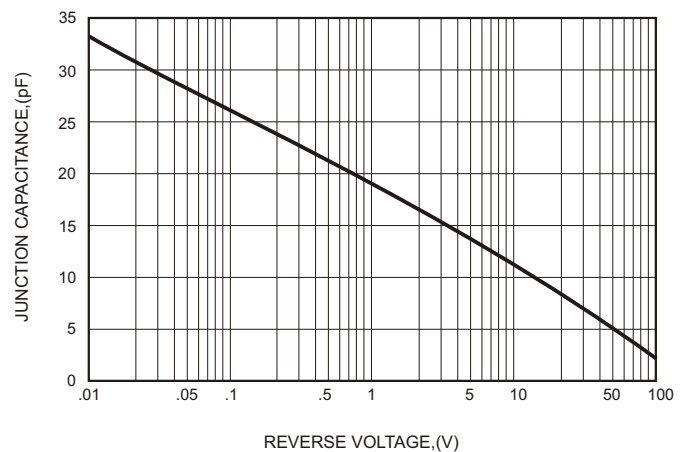
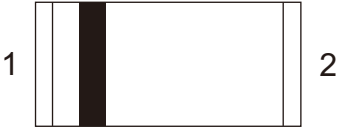



FIG.5-TYPICAL JUNCTION CAPACITANCE





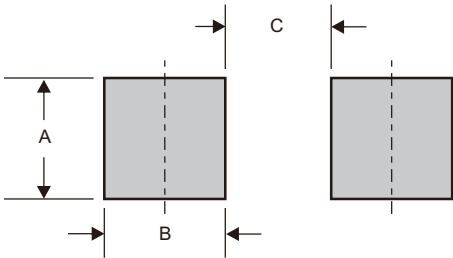
Pinning information

| Pin | Simplified outline | Symbol |
|----------------------------|--|---|
| Pin1 cathode Pin2 anode |  |  |

Marking

| Type number | Marking code |
|-------------|--------------|
| FFM101-M | F1 |
| FFM102-M | F2 |
| FFM103-M | F3 |
| FFM104-M | F4 |
| FFM105-M | F5 |
| FFM106-M | F6 |
| FFM107-M | F7 |

Suggested solder pad layout

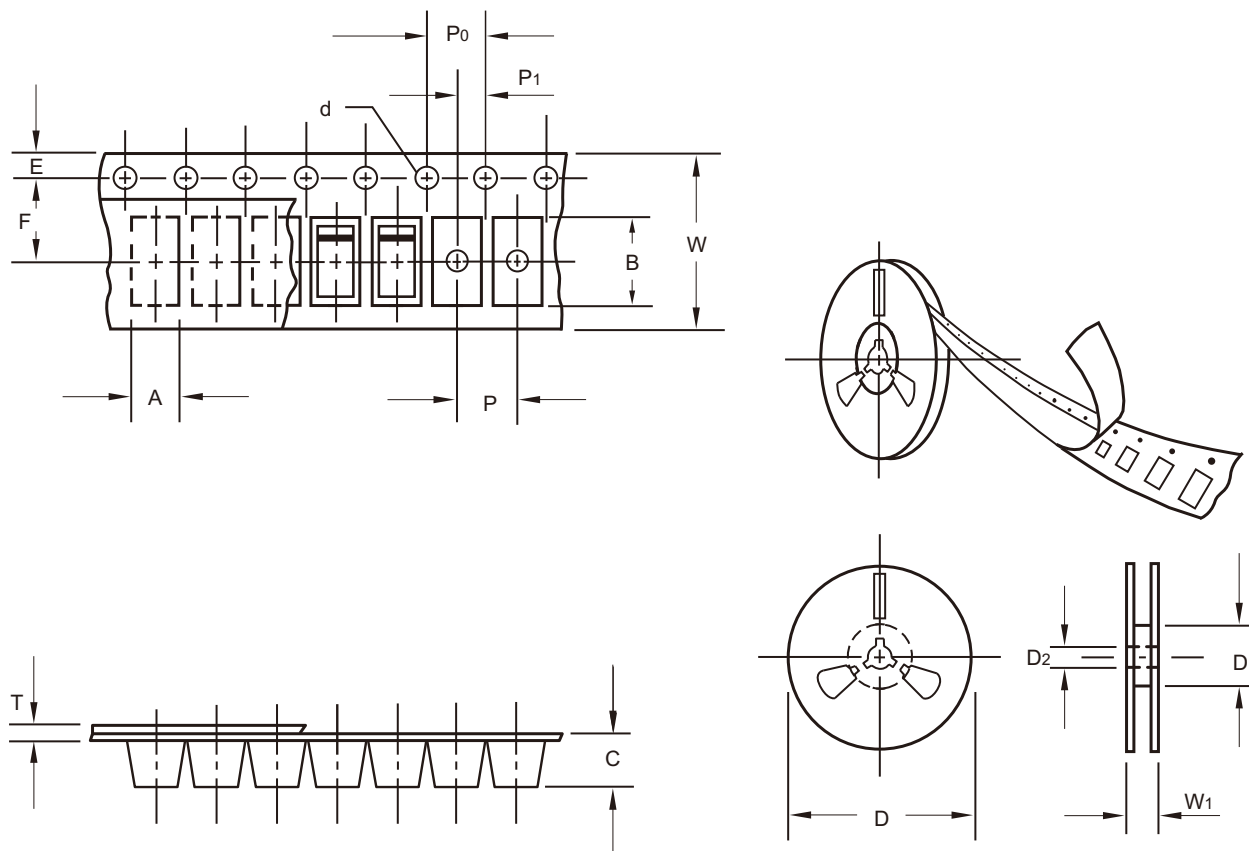


Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
|---------|--------------|--------------|--------------|
| SOD-123 | 0.075 (1.90) | 0.055 (1.40) | 0.075 (1.90) |



Packing information



unit:mm

| Item | Symbol | Tolerance | SOD-123 |
|---------------------------|--------|-----------|---------|
| Carrier width | A | 0.1 | 1.90 |
| Carrier length | B | 0.1 | 3.90 |
| Carrier depth | C | 0.1 | 1.68 |
| Sprocket hole | d | 0.1 | 1.50 |
| 13" Reel outside diameter | D | 2.0 | - |
| 13" Reel inner diameter | D1 | min | - |
| 7" Reel outside diameter | D | 2.0 | 178.00 |
| 7" Reel inner diameter | D1 | min | 62.00 |
| Feed hole diameter | D2 | 0.5 | 13.00 |
| Sprocket hole position | E | 0.1 | 1.75 |
| Punch hole position | F | 0.1 | 3.50 |
| Punch hole pitch | P | 0.1 | 4.00 |
| Sprocket hole pitch | P0 | 0.1 | 4.00 |
| Embossment center | P1 | 0.1 | 2.00 |
| Overall tape thickness | T | 0.1 | 0.23 |
| Tape width | W | 0.3 | 8.00 |
| Reel width | W1 | 1.0 | 11.40 |

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

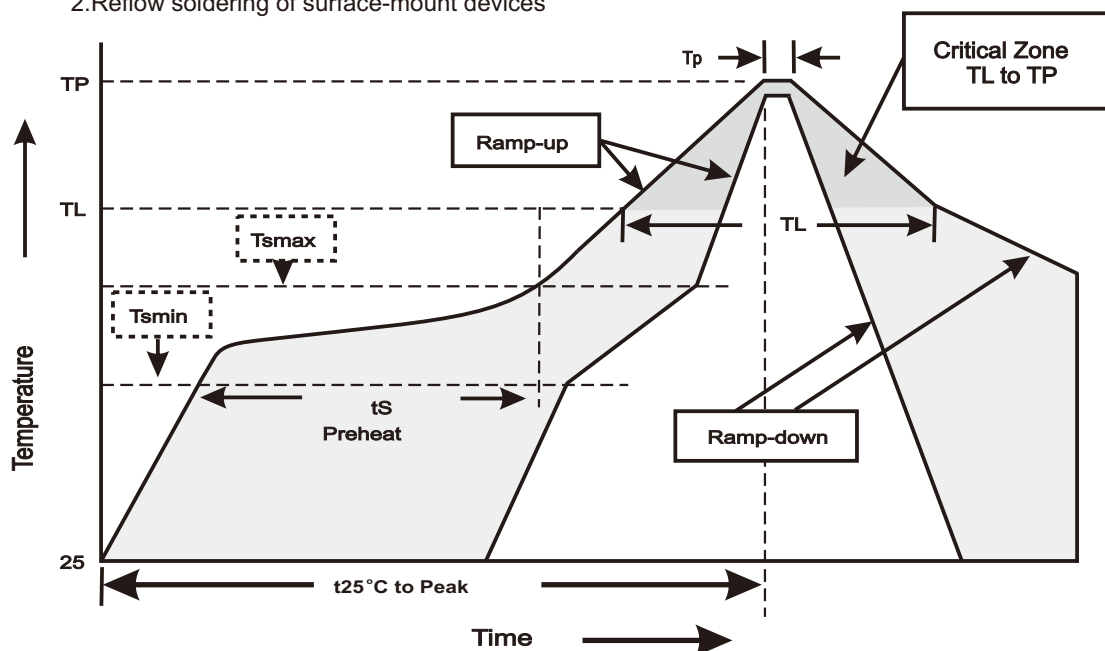


Reel packing

| PACKAGE | REEL SIZE | REEL (pcs) | COMPONENT SPACING (m/m) | BOX (pcs) | INNER BOX (m/m) | REEL DIA, (m/m) | CARTON SIZE (m/m) | CARTON (pcs) | APPROX. GROSS WEIGHT (kg) |
|---------|-----------|---------------|-------------------------------|--------------|-----------------------|--------------------|-------------------------|-----------------|---------------------------------|
| SOD-123 | 7" | 2,500 | 4.0 | 25,000 | 183*183*123 | 178 | 382*262*387 | 200,000 | 9.5 |

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40 °C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

| Profile Feature | Soldering Condition |
|---|-----------------------------|
| Average ramp-up rate(T _L to T _P) | <3 °C/sec |
| Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s) | 150°C 200°C 60~120sec |
| T _{smmax} to T _L -Ramp-upRate | <3°C/sec |
| Time maintained above: -Temperature(T _L) -Time(t _L) | 217°C 60~260sec |
| Peak Temperature(T _P) | 255°C-0/+5°C |
| Time within 5°C of actual Peak Temperature(t _p) | 10~30sec |
| Ramp-down Rate | <6°C/sec |
| Time 25°C to Peak Temperature | <6minutes |



High reliability test capabilities

| Item Test | Conditions | Reference |
|-----------------------------------|--|-------------------------------|
| 1. Solder Resistance | at $260 \pm 5^{\circ}\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16'' \pm 1/32''$ | MIL-STD-750D METHOD-2031 |
| 2. Solderability | at $245 \pm 5^{\circ}\text{C}$ for 5 sec. | MIL-STD-202F METHOD-208 |
| 3. High Temperature Reverse Bias | $V_R = 80\%$ rate at $T_J = 150^{\circ}\text{C}$ for 168 hrs. | MIL-STD-750D METHOD-1026 |
| 4. Forward Operation Life | Rated average rectifier current at $T_A = 25^{\circ}\text{C}$ for 500hrs. | MIL-STD-750D METHOD-1027 |
| 5. Intermittent Operation Life | $T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles. | MIL-STD-750D METHOD-1036 |
| 6. Pressure Cooker | $15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs. | JESD22-A102 |
| 7. Temperature Cycling | -55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles. | MIL-STD-750D METHOD-1051 |
| 8. Thermal Shock | 0°C for 5 min. rise to 100°C for 5 min. total 10 cycles. | MIL-STD-750D METHOD-1056 |
| 9. Forward Surge | 8.3ms single half sine-wave superimposed on rated load, one surge. | MIL-STD-750D METHOD-4066-2 |
| 10. Humidity | at $T_A = 85^{\circ}\text{C}$, RH=85% for 1000hrs. | MIL-STD-750D METHOD-1038 |
| 11. High Temperature Storage Life | at 175°C for 1000 hrs. | MIL-STD-750D METHOD-1031 |